

Strategic Wireless Applications
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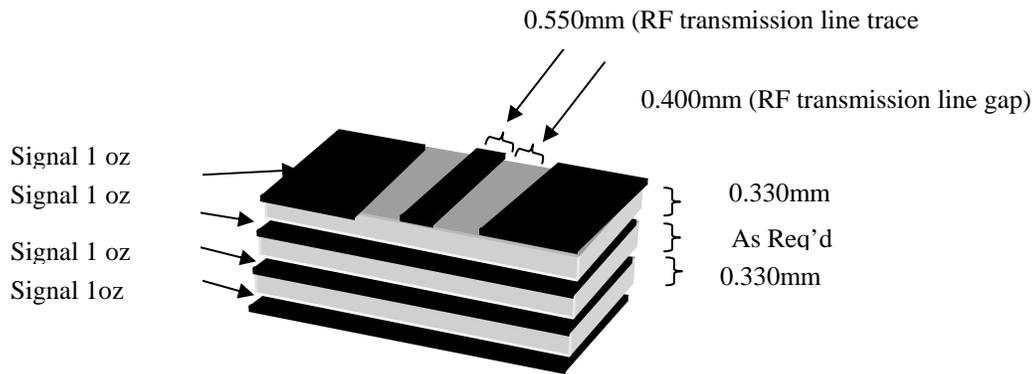
PCB Project/Physical Description

EV Kit Part Number: MAX2769BEVKIT# Rev: A

Quantity : Turn (working days) :

Layers: 4 PCB Thickness: 1.575mm Dielectric: High Tg FR-4 (or equivalent) RoHS compliant material ONLY

RF characteristic impedance: 50Ω +/-10% Dielectric Constant: 4.5



Min. drill size(finish): 0.2mm

Min. line width/spacing: 0.16mm/0.16mm

Plating: Immersion Gold Weight: 2 – 10 u" Immersion Au over 100u" Ni

Board dimensions: 76.20mm X 76.20mm # of surface mount pads (top): 264 # of surface mount pads (bottom): 462

Approx. # of holes: 631 Silkscreen: White, Both Sides Solder Mask: LPI Green, Both Sides

Scoring (location): _____ . Additional features: _____ .

Tolerance

Board Dimensions: 0.254mm
Plated Thru Holes: 0.076mm
Pattern to Pattern: 0.127mm
Solder Mask to Pattern: 0.127mm
Legend to Legend: 0.178mm
